SiRF 2009

The 9th Topical Meeting on
Silicon Monolithic Integrated Circuits in RF Systems

Held during the Radio and Wireless Week
January 19-21, 2009, San Diego, California, USA

Call for Papers

This 9th *Topical Meeting on Silicon Monolithic Integrated Circuits in RF Systems (SiRF 2009)* continues to be the only conference devoted to Si-based devices, passives, integrated circuits, and applications for high-frequency systems. Over three days, papers and sessions will highlight the significant technological advances of this dynamic field, as well as provide a unique forum for the presentation of new ideas and candid exchange on emerging challenges and opportunities. Invited tutorial talks from international experts will be presented in key topical areas. A student paper competition will be held, and prizes will be given at the conference banquet.

Technical papers are solicited in the following areas, but all papers related to Si-based RF systems are welcome:

- **RF Circuits:** RF Building blocks (LNA, mixer, VCO, PA, drivers, switches, filters, frequency synthesizers), integrated transceivers, high-speed DAC and ADC, integrated transponders, analog/mixed-signal circuit blocks. Both RF CMOS and SiGe BiCMOS designs are welcome.
- **Si Millimeter Wave ICs:** millimeter wave circuits and systems for non-destructive testing, automotive radar, high-bit rate wireless communication, concealed weapon detection and bio-molecular spectroscopy.
- **RF Systems and Architectures:** WLAN, Bluetooth, 802.1x, Telemetry, RFID, system-on-a-chip (SoC) and system-in-a-package (SiP) solutions, integration of Si-based photonic elements.
- **Devices and Modeling:** physics, optimization, layout, testing, and modeling of transistors and passives.
- **Materials:** epitaxial growth, strain engineering, characterization methods, stability issues, defects.
- **IC Technologies:** novel device structures, integration issues, heterogeneously integrated devices and circuits, interconnects, packaging.
- **Passives and MEMS:** inductors, capacitors, thin film resistors, transmission lines, integrated antenna, transformers, RF MEMS, micro-machining for improved passives, integration with Si-based circuits and systems, FBARs.
- **Emerging Technologies:** Nano, quantum, optical, and THz technology devices and circuits, flexible RF.

Submission Deadline: July 20, 2008

PAPER SUBMISSION GUIDELINES

Authors must submit a two to four page manuscript in *pdf* format online and must clearly indicate how the work advances the-state-of-the-art. Papers should include: 1) the names of all authors and their affiliations, 2) whether this is a student paper, and 3) the mailing address, phone number, fax number, and email address of the corresponding author. Papers submitted to SiRF 2009 must NOT be submitted to the other two conferences of the *Radio and Wireless Week.*

MEETING DETAILS

This meeting will be held during the *Radio and Wireless Week* in San Diego, CA with joint sessions between *Radio and Wireless Symposium (RWS)* and *Power Amplifier Symposium (PAS)*. Our popular single session format allows active interactions between all participants. A refereed IEEE conference proceeding will be published, and a best student paper competition will be held. Questions on the conference details and paper submission procedure may be found at the conference web site: http://www.eng.auburn.edu/~niuguof/sirf/.

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Dimitrios Peroulis, *Purdue U.*
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